What is claimed is:

1. A system for decapsulating an integrated circuit package that is mounted to a printed circuit board, comprising:

a source of a decapsulation fluid;

a tray that supports the printed circuit board;

an injection head that is located adjacent to the integrated circuit package, said injection head has a nozzle and a return port that are coupled to said source of decapsulation fluid to introduce the decapsulation fluid to the integrated circuit package; and,

a gasket that seals said injection head to the integrated circuit package.

2. The system as recited in claim 1, further comprising a clamp that clamps said injection head onto the integrated circuit package.

3. The system as recited in claim 1, wherein said source of decapsulation fluid includes an extender that is coupled to a nozzle that provides the decapsulation fluid.

4. The system as recited in claim 3, further comprising a pair of tubes that couple said extender to said injection head.

5. The system as recited in claim 4, further comprising a pair of valves that control a flow of the decapsulation fluid through said tubes.

6. The system as recited in claim 1, wherein said tray includes a stub that supports the printed circuit board and which is plugged into a substrate of said tray.

7. A system for decapsulating an integrated circuit package that is mounted to a printed circuit board, comprising:

a substrate;

a clamp that is mounted to said substrate, said clamp having a leg portion that supports the printed circuit board;

a stub that is plugged into said substrate and which supports the printed circuit board;

a decapsulation fluid unit which has a nozzle that provides a decapsulation fluid, and a return port that receives the decapsulation fluid;

an extender that has an intake port that is in fluid communication with an outlet port of said extender and said nozzle of said decapsulation fluid unit, and an exhaust port that is in fluid communication with an inlet port of said extender and said return port of said decapsulation fluid unit;

an injection head that is clamped to the integrated circuit package by said clamp, said injection head has a nozzle that is in fluid communication with an inlet port of said injection head, and a return port that is in fluid communication with an outlet port of said injection head;

a first tube that couples said outlet port of said extender with said inlet port of said injection head;

a second tube that couples said inlet port of said extender with said outlet port of said injection head; and,

a gasket that seals said injection head to the integrated circuit package.

8. The system as recited in claim 4, further comprising a pair of valves that control a flow of the decapsulation fluid through said tubes.

9. A method for decapsulating an integrated circuit package that is mounted to a printed circuit board, comprising the steps of:

a) providing an injection head that sprays a decapsulation fluid;

b) placing the printed circuit board onto a tray;

c) clamping said injection head onto the integrated circuit package; and,

d) spraying the decapsulation fluid onto the integrated circuit package.

10. The method as recited in claim 9, further comprising the step of moving a stub that is plugged into said tray and which supports the printed circuit board before the printed circuit board is placed onto said tray.